

E Series Power MOSFET



RoHS
COMPLIANT
HALOGEN
FREE

PRODUCT SUMMARY

| | | |
|---|-----------------|-----|
| V_{DS} (V) at T_J max. | 650 | |
| $R_{DS(on)}$ max. at 25 °C (Ω) | $V_{GS} = 10$ V | 0.6 |
| Q_g max. (nC) | 40 | |
| Q_{gs} (nC) | 5 | |
| Q_{gd} (nC) | 9 | |
| Configuration | Single | |

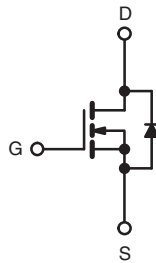
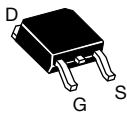
FEATURES

- Low Figure-of-Merit (FOM) $R_{on} \times Q_g$
- Low Input Capacitance (C_{iss})
- Reduced Switching and Conduction Losses
- Ultra Low Gate Charge (Q_g)
- Avalanche Energy Rated (UIS)
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and Telecom Power Supplies
- Switch Mode Power Supplies (SMPS)
- Power Factor Correction Power Supplies (PFC)
- Lighting
 - High-Intensity Discharge (HID)
 - Fluorescent Ballast Lighting
- Industrial
 - Welding
 - Induction Heating
 - Motor Drives
 - Battery Chargers
 - Renewable Energy
 - Solar (PV Inverters)

DPAK
(TO-252)



N-Channel MOSFET

ORDERING INFORMATION

| | |
|---------------------------------|-----------------|
| Package | DPAK (TO-252) |
| Lead (Pb)-free and Halogen-free | SiHD7N60E-GE3 |
| | SiHD7N60ET-GE3 |
| | SiHD7N60ETR-GE3 |
| | SiHD7N60ETL-GE3 |

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT | |
|--|------------------|-------------------------------------|------|------|
| Drain-Source Voltage | V_{DS} | 600 | V | |
| Drain-Source Voltage | | $T_C = -25$ °C, $I_D = 250$ μ A | | 575 |
| Gate-Source Voltage | | ± 20 | | |
| Gate-Source Voltage AC ($f > 1$ Hz) | V_{GS} | 30 | | |
| Continuous Drain Current ($T_J = 150$ °C) | V_{GS} at 10 V | $T_C = 25$ °C | 7 | A |
| | | $T_C = 100$ °C | 5 | |
| Pulsed Drain Current ^a | I_{DM} | 18 | | |
| Linear Derating Factor | | 0.63 | W/°C | |
| Single Pulse Avalanche Energy ^b | E_{AS} | 43 | mJ | |
| Maximum Power Dissipation | P_D | 78 | W | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to + 150 | °C | |
| Drain-Source Voltage Slope | dV/dt | $T_J = 125$ °C | 37 | V/ns |
| Reverse Diode dV/dt ^d | | 3 | | |
| Soldering Recommendations (Peak Temperature) | for 10 s | 300° | °C | |


Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 13.8$ mH, $R_g = 25$ Ω , $I_{AS} = 2.5$ A.
- 1.6 mm from case.

d. $I_{SD} \leq I_D$, $dI/dt = 100 \text{ A}/\mu\text{s}$, starting $T_J = 25 \text{ }^\circ\text{C}$.

| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R_{thJA} | - | 62 | °C/W |
| Maximum Junction-to-Case (Drain) | R_{thJC} | - | 1.6 | |

SPECIFICATIONS ($T_J = 25 \text{ }^\circ\text{C}$, unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|---------------------|---|------|------|-----------|---------------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$ | 609 | - | - | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | Reference to $25 \text{ }^\circ\text{C}$, $I_D = 1 \text{ mA}$ | - | 0.68 | - | V/°C |
| Gate-Source Threshold Voltage (N) | $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$ | 2 | - | 4 | V |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = \pm 20 \text{ V}$ | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 600 \text{ V}$, $V_{GS} = 0 \text{ V}$ | - | - | 1 | μA |
| | | $V_{DS} = 480 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 125 \text{ }^\circ\text{C}$ | - | - | 10 | |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS} = 10 \text{ V}$ $I_D = 3.5 \text{ A}$ | - | 0.5 | 0.6 | Ω |
| Forward Transconductance | g_{fs} | $V_{DS} = 50 \text{ V}$, $I_D = 3.5 \text{ A}$ | - | 1.9 | - | S |
| Dynamic | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0 \text{ V}$, $V_{DS} = 100 \text{ V}$, $f = 1 \text{ MHz}$ | - | 680 | - | pF |
| Output Capacitance | C_{oss} | | - | 39 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 5 | - | |
| Effective Output Capacitance, Energy Related ^a | $C_{o(er)}$ | $V_{DS} = 0 \text{ V to } 480 \text{ V}$, $V_{GS} = 0 \text{ V}$ | - | 34 | - | pF |
| Effective Output Capacitance, Time Related ^b | $C_{o(tr)}$ | | - | 100 | - | |
| Total Gate Charge | Q_g | $V_{GS} = 10 \text{ V}$ $I_D = 3.5 \text{ A}$, $V_{DS} = 480 \text{ V}$ | - | 20 | 40 | nC |
| Gate-Source Charge | Q_{gs} | | - | 5 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 9 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 480 \text{ V}$, $I_D = 3.5 \text{ A}$, $V_{GS} = 10 \text{ V}$, $R_g = 9.1 \Omega$ | - | 13 | 26 | ns |
| Rise Time | t_r | | - | 13 | 26 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 24 | 48 | |
| Fall Time | t_f | | - | 14 | 28 | |
| Gate Input Resistance | R_g | $f = 1 \text{ MHz}$, open drain | - | 1.1 | - | Ω |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source-Drain Diode Current | I_S | MOSFET symbol showing the integral reverse p - n junction diode  | - | - | 7 | A |
| Pulsed Diode Forward Current | I_{SM} | | - | - | 18 | |
| Diode Forward Voltage | V_{SD} | $T_J = 25 \text{ }^\circ\text{C}$, $I_S = 3.5 \text{ A}$, $V_{GS} = 0 \text{ V}$ | - | - | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $T_J = 25 \text{ }^\circ\text{C}$, $I_F = I_S = 3.5 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$, $V_R = 20 \text{ V}$ | - | 230 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | - | 1.9 | - | μC |
| Reverse Recovery Current | I_{RRM} | | - | 14 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
 b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

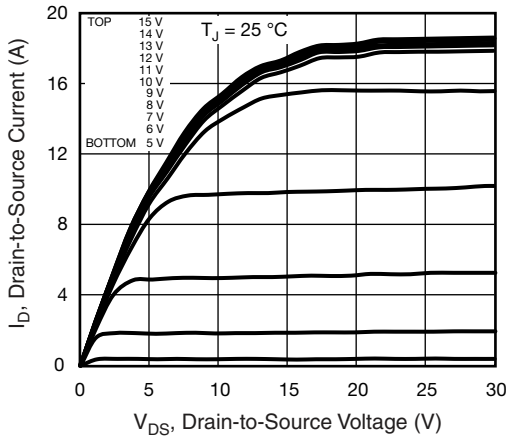


Fig. 1 - Typical Output Characteristics

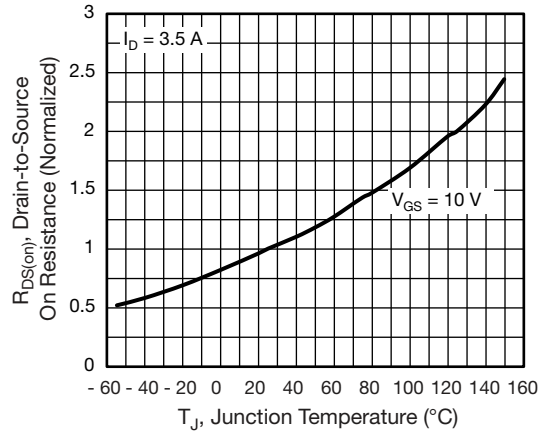


Fig. 4 - Normalized On-Resistance vs. Temperature

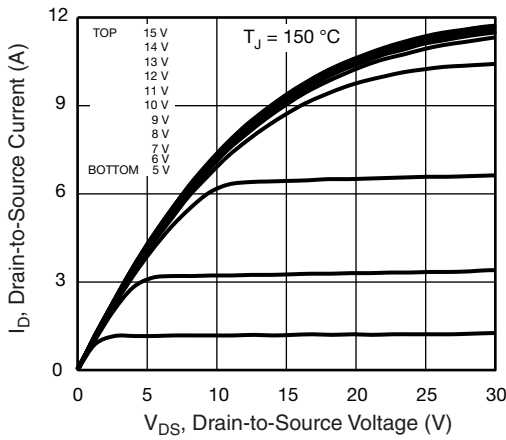


Fig. 2 - Typical Output Characteristics

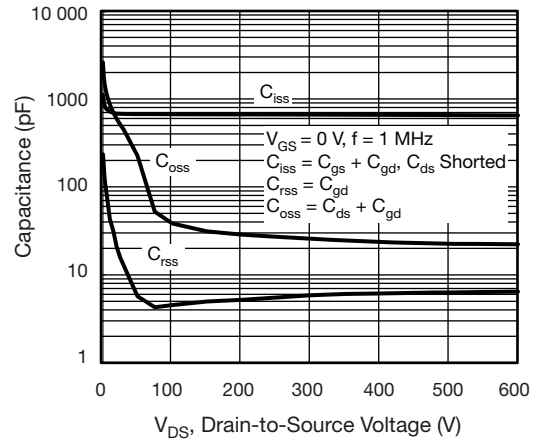


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

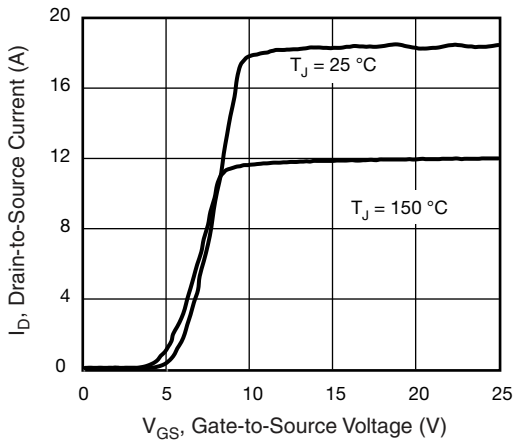


Fig. 3 - Typical Transfer Characteristics

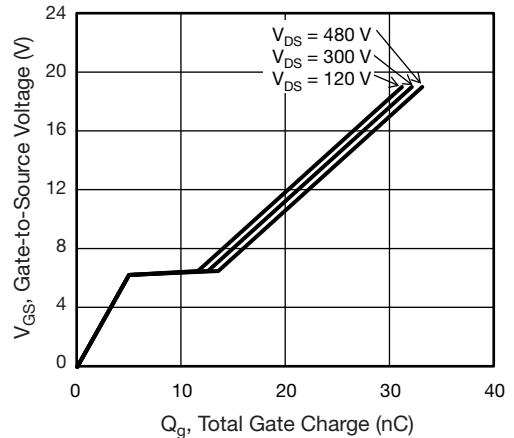


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

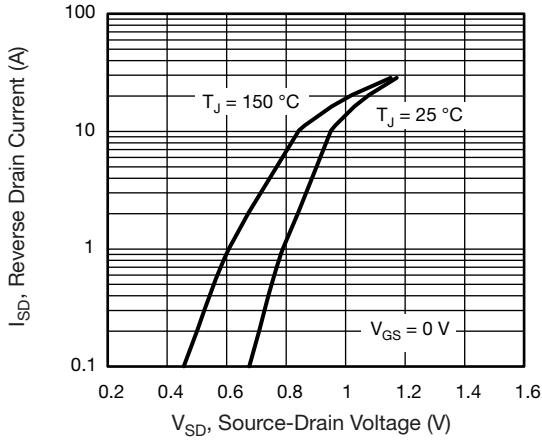


Fig. 7 - Typical Source-Drain Diode Forward Voltage

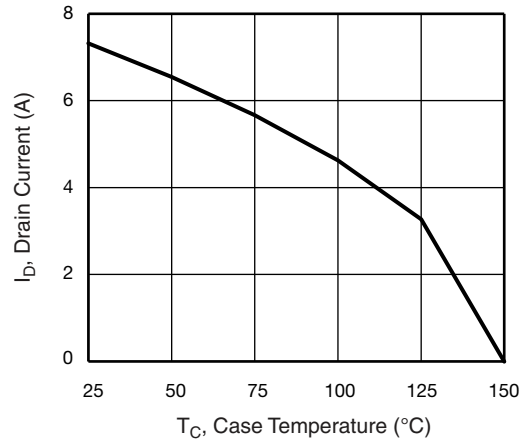


Fig. 9 - Maximum Drain Current vs. Case Temperature

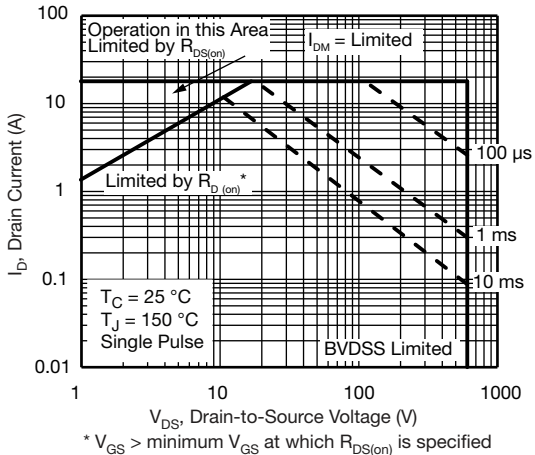


Fig. 8 - Maximum Safe Operating Area

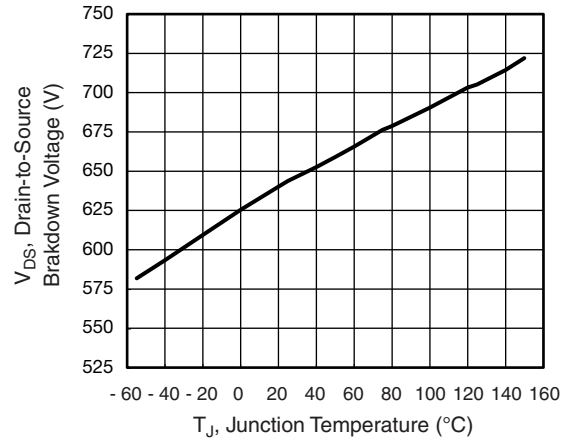


Fig. 10 - Temperature vs. Drain-to-Source Voltage

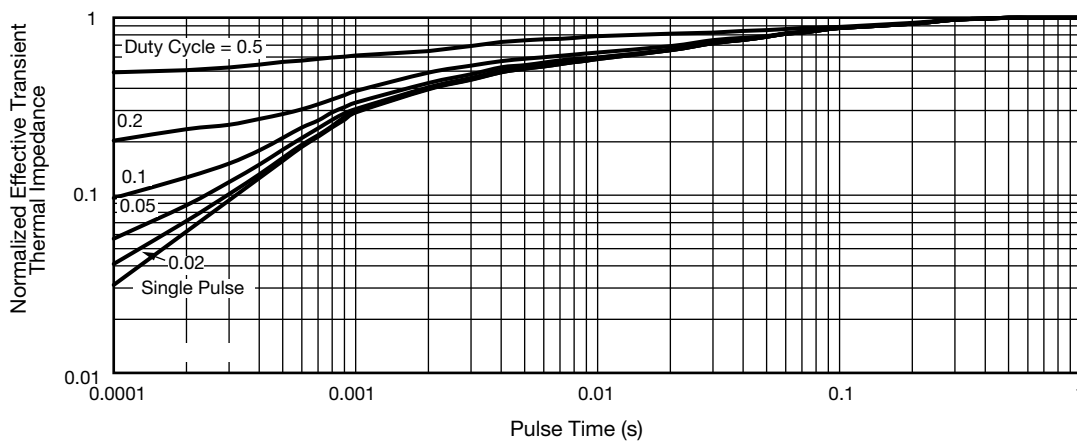


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

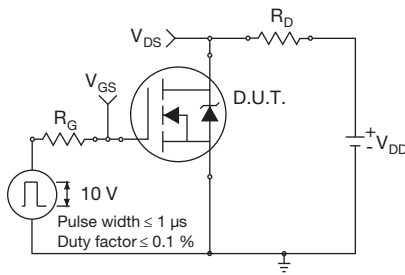


Fig. 12 - Switching Time Test Circuit

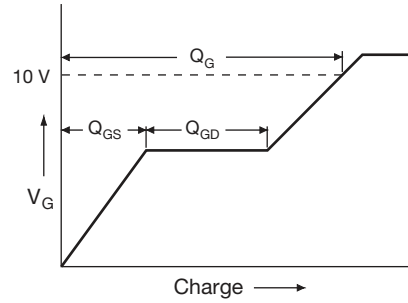


Fig. 16 - Basic Gate Charge Waveform

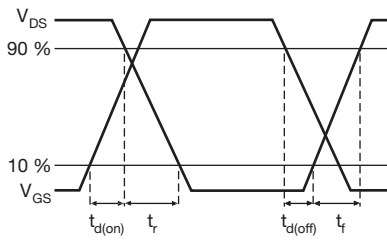


Fig. 13 - Switching Time Waveforms

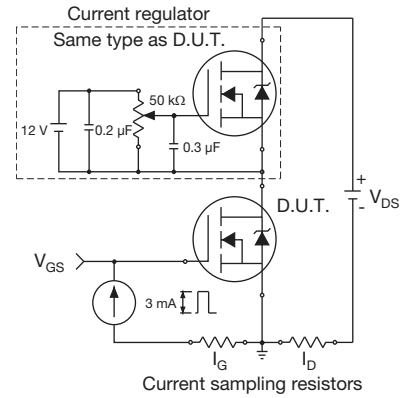


Fig. 17 - Gate Charge Test Circuit

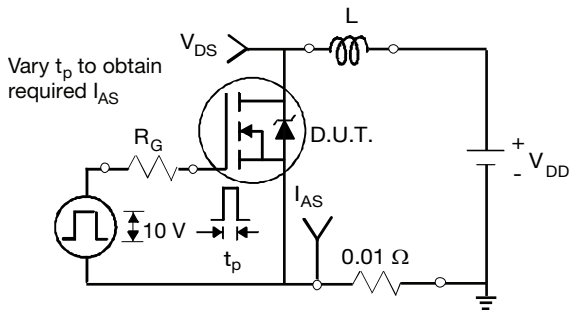


Fig. 14 - Unclamped Inductive Test Circuit

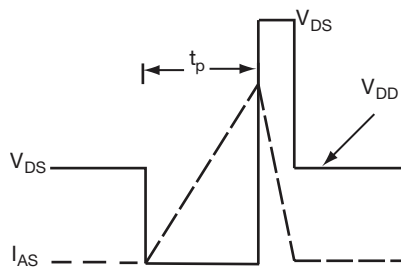
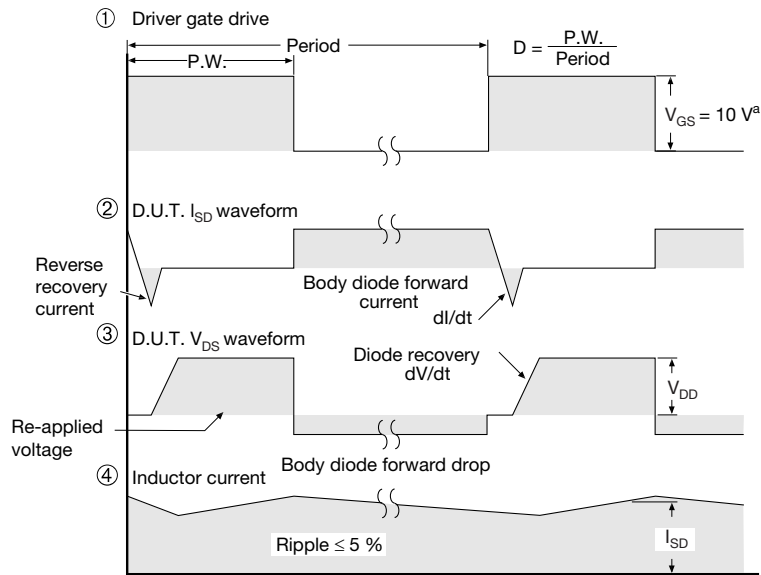
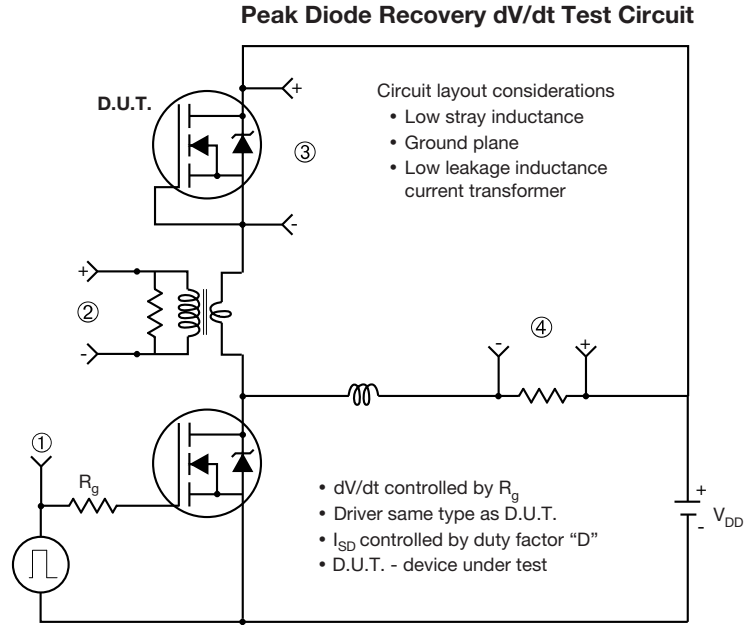


Fig. 15 - Unclamped Inductive Waveforms



Note
a. $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 18 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91510.

TO-252AA (HIGH VOLTAGE)



| DIM. | MILLIMETERS | | INCHES | |
|------|-------------|-------|-----------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| E | 6.40 | 6.73 | 0.252 | 0.265 |
| L | 1.40 | 1.77 | 0.055 | 0.070 |
| L1 | 2.743 REF | | 0.108 REF | |
| L2 | 0.508 BSC | | 0.020 BSC | |
| L3 | 0.89 | 1.27 | 0.035 | 0.050 |
| L4 | 0.64 | 1.01 | 0.025 | 0.040 |
| D | 6.00 | 6.22 | 0.236 | 0.245 |
| H | 9.40 | 10.40 | 0.370 | 0.409 |
| b | 0.64 | 0.88 | 0.025 | 0.035 |
| b2 | 0.77 | 1.14 | 0.030 | 0.045 |
| b3 | 5.21 | 5.46 | 0.205 | 0.215 |
| e | 2.286 BSC | | 0.090 BSC | |
| A | 2.20 | 2.38 | 0.087 | 0.094 |
| A1 | 0.00 | 0.13 | 0.000 | 0.005 |
| c | 0.45 | 0.60 | 0.018 | 0.024 |
| c2 | 0.45 | 0.58 | 0.018 | 0.023 |
| D1 | 5.30 | - | 0.209 | - |
| E1 | 4.40 | - | 0.173 | - |
| θ | 0' | 10' | 0' | 10' |

ECN: S-81965-Rev. A, 15-Sep-08
 DWG: 5973

Notes

1. Package body sizes exclude mold flash, protrusion or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 0.10 mm per side.
2. Package body sizes determined at the outermost extremes of the plastic body exclusive of mold flash, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.
3. The package top may be smaller than the package bottom.
4. Dimension "b" does not include dambar protrusion. Allowable dambar protrusion shall be 0.10 mm total in excess of "b" dimension at maximum material condition. The dambar cannot be located on the lower radius of the foot.

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads
Dimensions in Inches/(mm)

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.